



30V N-Channel Trench Power MOSFET

General Description

The SJA3400 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a wide variety of applications.

Features

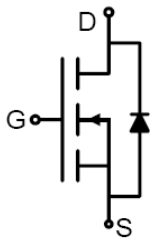
- Low Gate Charge
- High Power and current handing capability
- Lead free product is acquired

Application

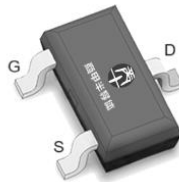
- PWM Applications
- Load Switch
- Power Management

Key Performance Parametes

Parameter	Value	Unit
V_{DS}	30	V
$R_{DS(ON_TYP)}$	17.1	mΩ
I_D	6.5	A
Q_G	10	nC



Schematic Diagram



SOT-23-3L top view



Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJA3400	3400	SOT-23	Tape	\	\	3000 Pcs

Table 1. Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V_{DS}	Drain-Source Voltage ($V_{GS}=0\text{V}$)	30	V
V_{GS}	Gate-Source Voltage ($V_{DS}=0\text{V}$)	± 20	V
I_D	Drain Current-Continuous($T_A=25^{\circ}\text{C}$)	6.5	A
	Drain Current-Continuous($T_A=100^{\circ}\text{C}$)	4.2	A
I_{DM} (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	26.4	A
P_D	Maximum Power Dissipation($T_A=25^{\circ}\text{C}$)	1.5	W
	Maximum Power Dissipation($T_A=100^{\circ}\text{C}$)	0.6	W
E_{AS}	Avalanche energy (Note 2)	30	mJ
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 150	$^{\circ}\text{C}$

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		83	$^{\circ}\text{C/W}$



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Table 3. Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250μA	30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V T _J =25°C			1	μA
		V _{DS} =30V, V _{GS} =0V T _J =125°C			100	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	0.45		1.25	V
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =2A		7.7		S
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =3A T _J =25°C		17.1	22.2	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =4.5V, I _D =2A T _J =25°C		18.3	24.3	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =2.5V, I _D =2A T _J =25°C		22	29	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =15V,V _{GS} =0V, f=1.0MHz		916		pF
C _{oss}	Output Capacitance			63.4		pF
C _{rss}	Reverse Transfer Capacitance			54.7		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1.0MHz		1.6		Ω
Switching Parameters						
t _{d(on)}	Turn-on Delay Time	V _{GS} =4.5V, V _{DS} =15V, R _L =5Ω, R _{GEN} =3Ω		4.2		nS
t _r	Turn-on Rise Time			17		nS
t _{d(off)}	Turn-Off Delay Time			93		nS
t _f	Turn-Off Fall Time			37		nS
Q _g	Total Gate Charge	V _{GS} =4.5V, V _{DS} =15V, I _D =3A		10		nC
Q _{gs}	Gate-Source Charge			1.6		nC
Q _{gd}	Gate-Drain Charge			2.5		nC
Source-Drain Diode Characteristics						
I _{SD}	Source-Drain Current (Body Diode)				6.5	A
V _{SD}	Forward on Voltage ^(Note 3)	V _{GS} =0V, I _S =3A			1.2	V

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

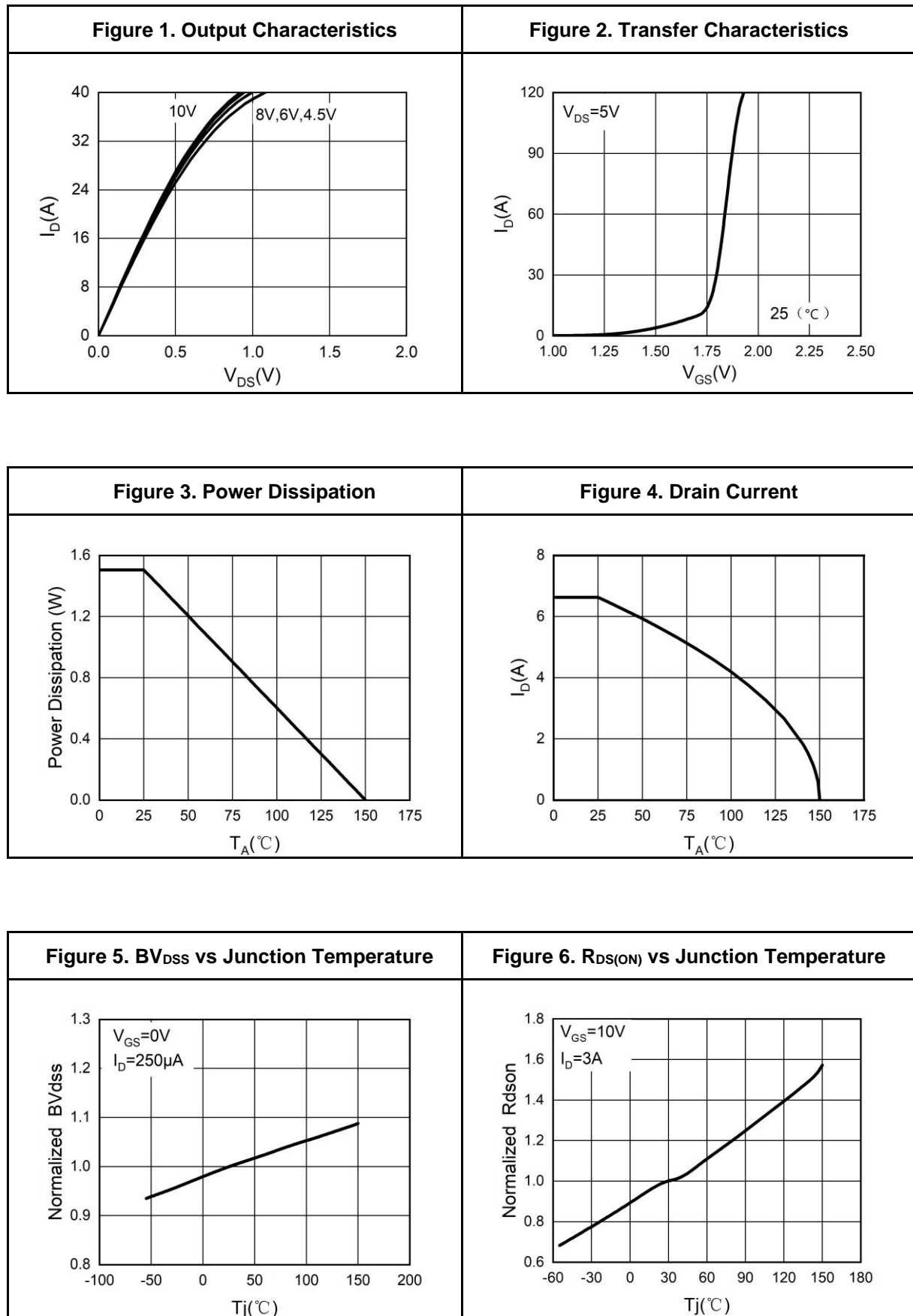
Notes 2.EAS condition: $T_J=25^{\circ}\text{C}, V_{DD}=30V, V_G=10V, R_g=25\Omega, L=0.5\text{mH}$.

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.



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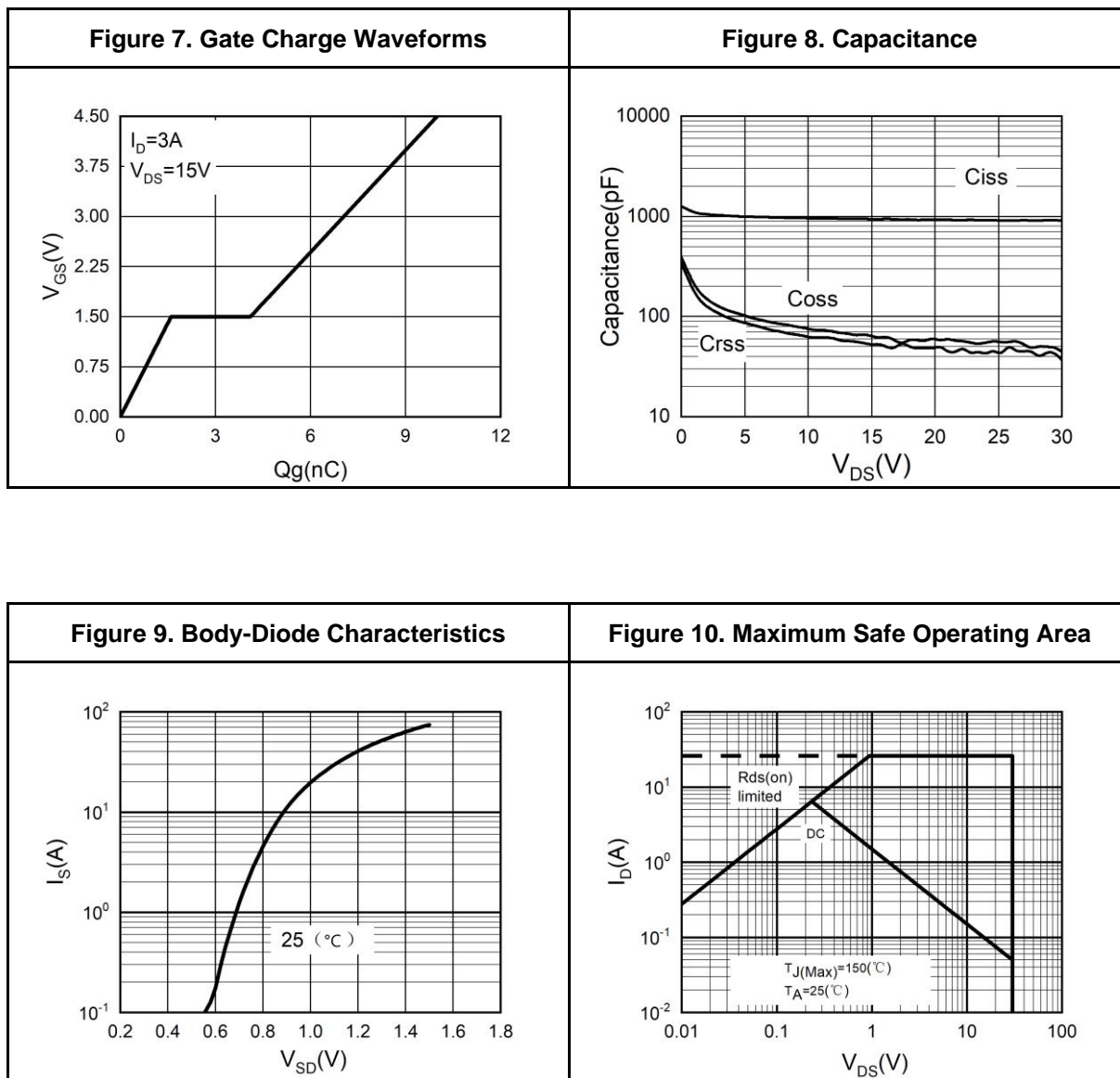
Typical Electrical And Thermal Characteristics (Curves)





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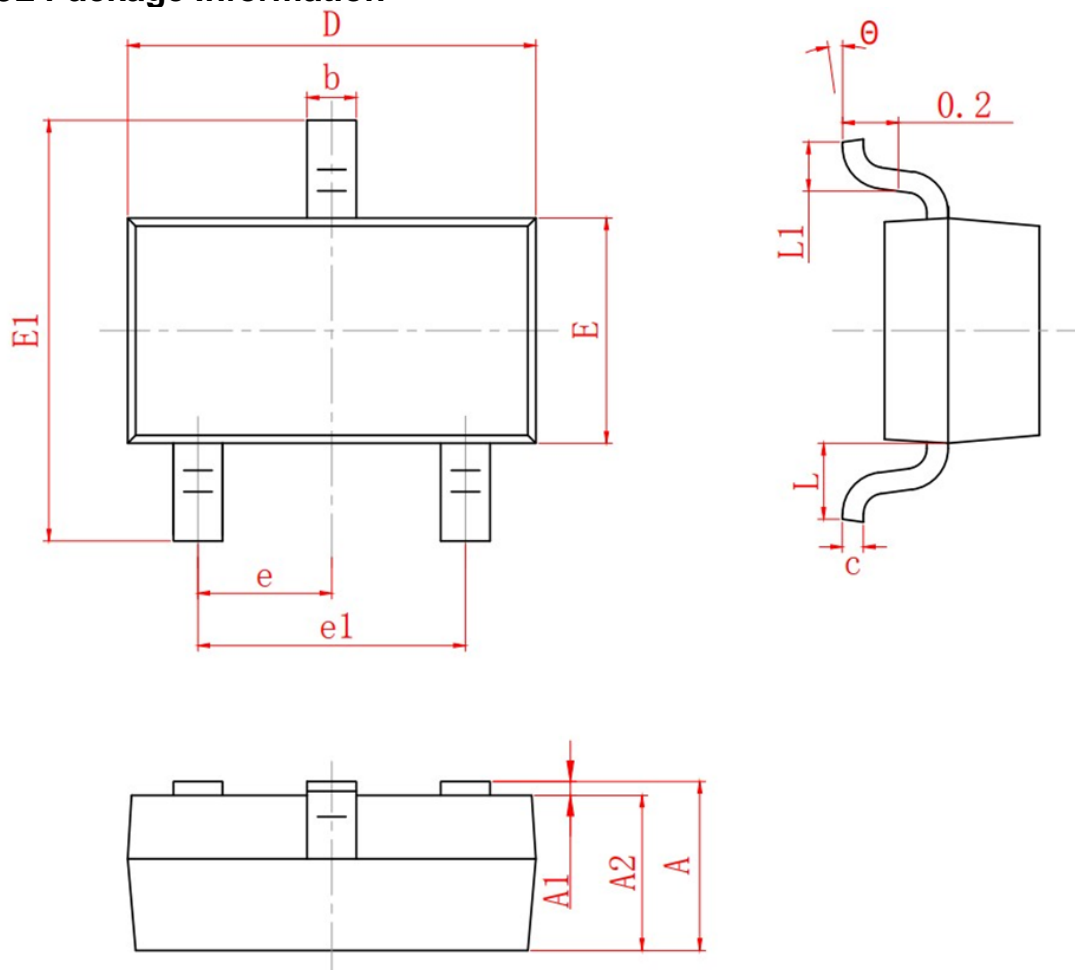
Typical Electrical And Thermal Characteristics (Curves)





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SOT-23-3L Package Information



SYMBOL	MIN	NOM	MAX
A	0.90	1.05	1.20
A1	0.00	0.05	0.10
A2	0.90	1.00	1.10
b	0.30	0.40	0.50
c	0.08	0.10	0.15
D	2.80	2.90	3.00
E	1.50	1.60	1.70
E1	2.65	2.80	2.95
L	0.30	0.40	0.50
θ	0°	5°	10°
L1	0.55 REF		
e	0.95 BSC		
e1	1.90 REF		



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